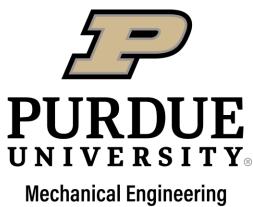


N I V E R S I T ' Mechanical Engineering During semiconductor chip production, incidental defects develop hot spots which are locations of high thermal flux. Hot spots beget extreme temperatures that decrease product reliability. SCS Solutions presents an automated hot spot detection device which is cost-competitive and requires minimal interaction.

> **Operation Procedure** Load samples onto acrylic raised plate & apply location inputs to program interface 2. Run program and review results 3. Replace verified chips back onto the production line





Performance Comp.			
Req.	SCS	Sentris	Liquid Crystal
Accuracy (Desired: ± 2.5°C)	± 2°C	± 2°C	± 1°C
Test Time (Desired: 10 mins)	3 mins / <9 chips	5 mins / chip	1 mins / chip
Costs (Desired: < \$5000)	\$3600	~\$10,000	~\$8700 (10,000 single uses)
intenance Desired: 100,000 cycles)	100,000 cycles	100,000 cycles	N/A: Excess waste and runoff

Potential Improvements

- 1. Improve analysis model to account for transience of heat input
- 2. Integrate the detector into an assembly line
- 3. Investigate the performance of higher resolution IR cameras with differing focal lengths, lenses, and other criteria

Contributors

SCS Solutions would like to thank Dr. Devahdhanush for his guidance and support throughout the project.